

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| In Re U.S. Patent Application   |                     | Confirmation No.: 1669  |
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| Applicant:  | Komiya et al.       | I hereby certify that this correspondence is being deposited with the United Postal Service as first class mail in an envelope addressed to: Mail Stop AMENDMENT, Commissioner of Patents, P.O. Box |
| Serial No.:   | 10/679,031          |   |
| Filed:  | October 3, 2003     |   |
| For:  | SILICON WAFER AND ) | 1450, Alexandria, VA, 22313-1450.   |
| METHOD FOR MANUFACTURE THEREOF, ) AND METHOD OF EVALUATION OF SILICON ) WAFER ) |                     | January 11, 2007  |
| Examiner:   | M.J. Song           | Gerald T. Shekleton Reg. No. 27,466   |

## **AMENDMENT**

Mail Stop AMENDMENT Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

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## Dear Sir:

Art Unit:

The Office Action of July 14, 2006, has been carefully reviewed and the following amendments and remarks are made in response thereto.